# **BGR405**

NPN Silicon RF Transistor With Bias Circuitry

**Small Signal Discretes** 



### Edition 2008-06-06

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BGR405,	3GR405, NPN Silicon RF Transistor With Bias Circuitry					
Revision	History: 2008-06-06, Rev. 1.0					
Prevision	History: no previous version					
Page	Subjects (major changes since last revision)					

# **Trademarks**

 ${\sf SIEGET}^{\$} \ \text{is a registered trademark of Infineon Technologies AG}.$ 

Data Sheet 3 Rev. 1.0, 2008-06-06



NPN Silicon RF Transistor With Bias Circuitry\*

# **NPN Silicon RF Transistor With Bias Circuitry\***

## **Features**

- Noise figure NF = 1.0 dB at 0.4 GHz
- Gain  $S_{21}$  = 7.5 dB at 0.4 GHz
- On chip bias circuitry, 0.85 mA bias current at  $V_{\rm CC}$  = 1.2 V
- SIEGET ® 25 GHz  $f_T$ -Line
- Pb-free (RoHS compliant) package
- \* Short term description



# **Applications**

LNAs

### 2 **Description**

The BGR405 is a monolithic silicon amplifier with a NPN silicon RF transistor and integrated resistors for biasing.

Туре	Package	Marking
BGR405	SOT343	AVs

Note: ESD (Electrostatic discharge) sensitive device, observe handling precaution!

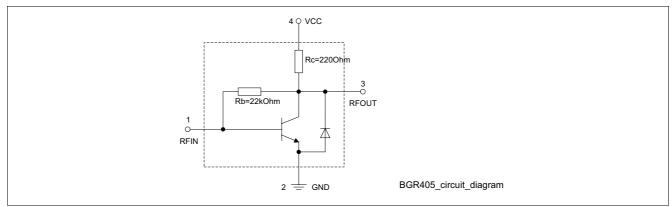


Figure 1 Circuit diagram

Note: Due to design there is an additional diode between emitter and collector, which does not effect normal operation for common emitter configuration.

**Data Sheet** Rev. 1.0, 2008-06-06



Description

Table 1 Pinning table

Pin	Function
1	RFIN
2	GND
3	RFOUT
4	VCC

# 2.1 Maximum Ratings

Note: All Voltages refer to GND-node

Table 2 Maximum ratings

Parameter	Symbol	Value	Unit
Current at pin VCC	$I_{CC}$	12	mA
Voltage at pin VCC	$V_{\sf CC}$	5	V
Current at pin RFIN	$I_{B}$	0.8	mA
Voltage at pin RFIN	$V_{B}$	2	V
Current at pin RFOUT <sup>1)</sup>	$I_{OUT}$	12	mA
Voltage at pin RFOUT	$V_{OUT}$	4.1	V
Total power dissipation <sup>2)</sup> $T_{\rm S}$ = 120 °C	$P_{tot}$	50	mW
Operation junction temperature range	$T_{jo}$	-65 150	°C
Storage junction temperature range	$T_{ m jstg}$	-65 150	°C

<sup>1)</sup> Applicable if VCC and RFOUT are shorted, otherwise a coupling capacitor at RFOUT is demanded

Note: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions even only for a short moment may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit. Absolute maximum ratings typically differ heavily from recommended operation conditions.

# 2.2 Thermal Resistance

Table 3 Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	$R_{thJS}$	≤ 595	K/W

<sup>1)</sup> For calculation of  $R_{\mathrm{thJA}}$  please refer to Application Note Thermal Resistance.

<sup>2)</sup>  $T_{\rm S}$  is measured on the emitter (GND) lead at the soldering point to the pcb

**Electrical Characteristics** 

# 3 Electrical Characteristics

Table 4 DC characteristics at  $T_A$  = 25 °C, unless otherwise specified

Parameter	Symbol		Values Unit Note /			
		Min.	Тур.	Max.		Test Condition
Device current	$I_{CC}$	0.6	0.85	1.1	mA	V <sub>CC</sub> = 1.2 V

Table 5 AC characteristics (measured in test circuit Figure 2; verified by random sampling)  $T_{\rm A}$  = 25 °C,  $V_{\rm CC}$  = 1.2 V,  $Z_0$  = 50  $\Omega$ , unless otherwise specified

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		<b>Test Condition</b>
Insertion power gain	S <sub>21</sub>		7.5		dB	F = 0.4 GHz
			7.0			f = 1.8 GHz
Reverse isolation	$S_{12}$		-37		dB	F = 0.4 GHz
			-25			f = 1.8 GHz
Noise figure, $Z_S = Z_{Sopt}$	NF		1.0		dB	F = 0.4 GHz
·			1.6			f = 1.8 GHz
Thid order intercept point at the	OIP <sub>3</sub>		-9		dBm	F = 0.4  GHz,
output <sup>1)</sup>						$V_{\rm CC}$ = 1.2 V
			14.5			f = 1.8 GHz,
						$V_{\rm CC}$ = 4 V
1 dB compression point at the output	$OP_{-1dB}$		-19		dBm	F = 0.4  GHz,
						$V_{\rm CC}$ = 1.2 V
			-0.5			f = 1.8  GHz,
						$V_{\rm CC}$ = 4 V
Return loss input	S <sub>11</sub>		-0.4		dB	F = 0.4 GHz
			-1.8			f = 1.8 GHz
Return loss output	$S_{22}$		-4.0		dB	F = 0.4 GHz
			-6.0			f = 1.8 GHz

<sup>1)</sup>  $OIP_3$  value depends on termination of all intermodulation frequency components. Termination used for this measurement is 50  $\Omega$  from 0.1 MHz to 6 GHz.

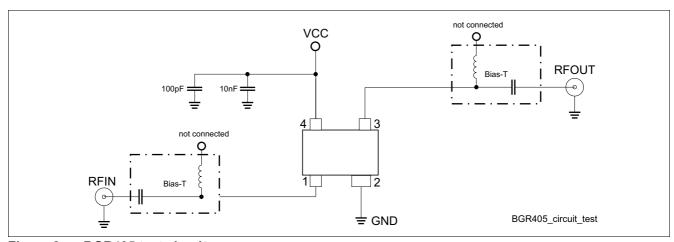


Figure 2 BGR405 test circuit



**Package Information** 

# 4 Package Information

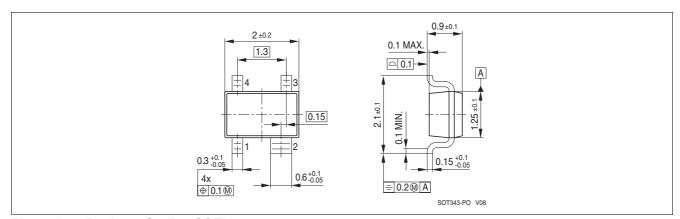


Figure 3 Package Outline SOT343

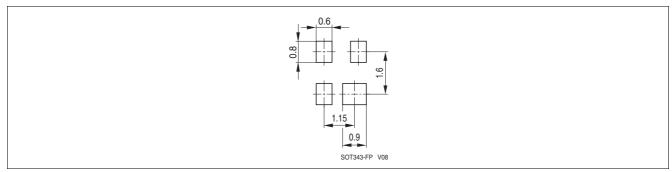


Figure 4 Footprint of SOT343

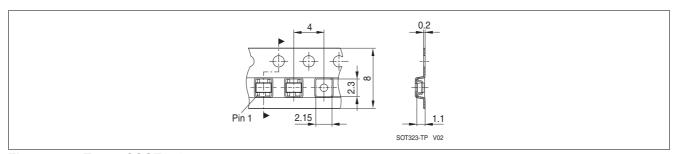


Figure 5 Tape of SOT343